

## DESCRIPTION

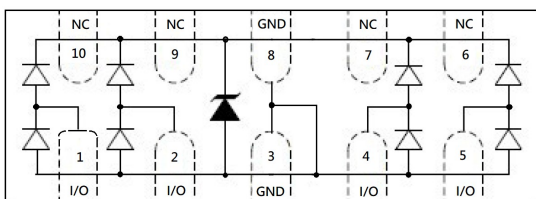
AZ1143-04F is an ultra-low capacitance Transient Voltage Suppressor (TVS) designed to protection for high-speed data interfaces. With typical capacitance of 0.2pF (I/O to I/O) only, AZ1143-04F is designed to protect parasitic-sensitive systems against over-voltage and over-current transient events. It complies with IEC 61000-4-2 (ESD), Level 4(±15KV air, ±8KV contact discharge), IEC61000-4-4 (electrical fast transient-EFT) (40A, 5/50ns), very fast charged device model (CDM)ESD and cable discharge event (CDE),etc.

AZ1143-04F uses ultra-small DFN2510 package. Each AZ1143-04F device can protect four high-speed data lines. The combined features of ultra-low capacitance, ultra-small size and high ESD robustness make AZ1143-04F the ideal for high-speed data ports and high-frequency lines (e.g., HDMI & DVI) applications. The low clamping voltage of the AZ1143-04F guarantees a minimum stress on the protected IC.

## ORDERING INFORMATION

- ✧ Package: DFN2510
- ✧ Marking: 3324P
- ✧ Material: Halogen free
- ✧ Packing: Tape & Reel
- ✧ Quantity per reel: 3,000pcs

## PIN CONFIGURATION



## FEATURES

- ✧ Transient protection for high-speed data lines  
IEC61000-4-2(ESD) ±20KV(Contact)  
±25KV(Air)
- IEC61000-4-4(EFT)40A(5/50ns)  
Cable Discharge Event(CDE)
- ✧ Package optimized for high-speed lines
- ✧ Ultra-small package(2.5mm\*1.0mm\*0.55mm)
- ✧ Protects four data lines
- ✧ Low capacitance: 0.2pF (I/O to I/O)
- ✧ Low leakage current
- ✧ Low clamping voltage
- ✧ Each I/O pin can withstand over 1000 ESD strikes for ±8KV contact discharge

## MACHANICAL DATA

- ✧ DFN2510 package
- ✧ Flammability Rating: UL 94V-0
- ✧ Terminal: Matte tin plated.
- ✧ High temperature soldering guaranteed:  
260°C/10s
- ✧ Packaging: Tape and Reel
- ✧ Reel size: 7 inch

## APPLICATIONS

- ✧ Serial ATA
- ✧ PCI Express
- ✧ MDDI Ports
- ✧ USB 2.0/3.0 Power and Data Line Protection
- ✧ Display Ports
- ✧ High Definition Multi-Media Interface (HDMI)
- ✧ Digital Visual Interface (DVI)

## CIRCUIT DIAGRAM



### ABSOLUTE MAXIMUM RATING

| Symbol    | Parameter                                                      | Value                | Units |
|-----------|----------------------------------------------------------------|----------------------|-------|
| $P_{PP}$  | Peak Pulse Power (8/20 $\mu$ s)                                | 56                   | W     |
| $V_{ESD}$ | ESD per IEC 61000-4-2 (Air)<br>ESD per IEC 61000-4-2 (Contact) | $\pm 25$<br>$\pm 20$ | kV    |
| $T_{OPT}$ | Operating Temperature                                          | -55/+125             | °C    |
| $T_{STG}$ | Storage Temperature                                            | -55/+150             | °C    |

### ELECTRICAL CHARACTERISTICS ( $T_{amb}=25^{\circ}C$ )

| Symbol    | Parameter                 | Test Condition                                       | Min | Typ | Max | Units   |
|-----------|---------------------------|------------------------------------------------------|-----|-----|-----|---------|
| $V_{RWM}$ | Reverse Working Voltage   | Any I/O pin to GND                                   |     |     | 3.3 | V       |
| $V_{BR}$  | Reverse Breakdown Voltage | $I_T = 1mA$<br>Any I/O pin to GND                    | 4.2 |     |     | V       |
| $I_R$     | Reverse Leakage Current   | $V_{RWM} = 3.3V$<br>Any I/O pin to GND               |     |     | 1.0 | $\mu A$ |
| $V_C$     | Clamping Voltage          | $I_{PP} = 1A, t_p = 8/20\mu s$<br>Any I/O pin to GND |     |     | 10  | V       |
|           |                           | $I_{PP} = 4A, t_p = 8/20\mu s$<br>Any I/O pin to GND |     |     | 14  | V       |
| $C_{ESD}$ | Parasitic Capacitance     | $V_R = 0V, f = 1MHz$<br>Between I/O and GND          |     | 0.4 | 0.5 | pF      |
| $C_{ESD}$ | Parasitic Capacitance     | $V_R = 0V, f = 1MHz$<br>Between I/O and I/O          |     | 0.2 | 0.3 | pF      |

Note: I/O pins are pin 1,2,4,5, GND pins are pin 3,8.

## ELECTRICAL CHARACTERISTICS CURVE

Fig 1 Power Derating Curve

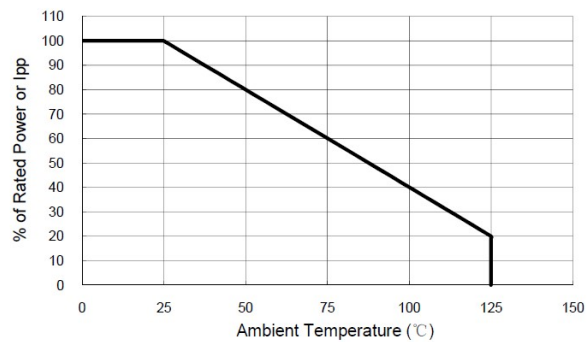


Fig 2 Clamping Voltage vs Peak Pulse Current

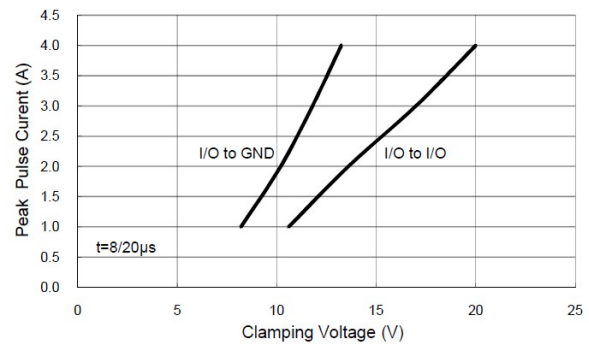


Fig 3 Voltage Sweeping of I/O to I/O

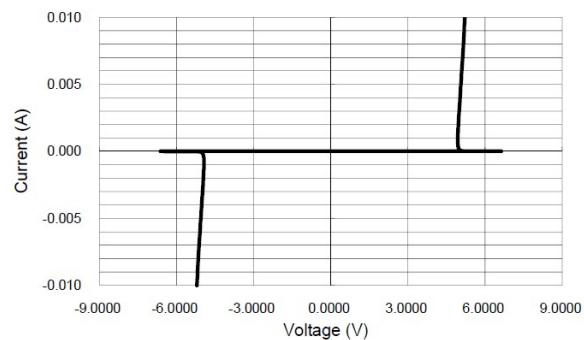


Fig 4 Voltage vs Capacitance

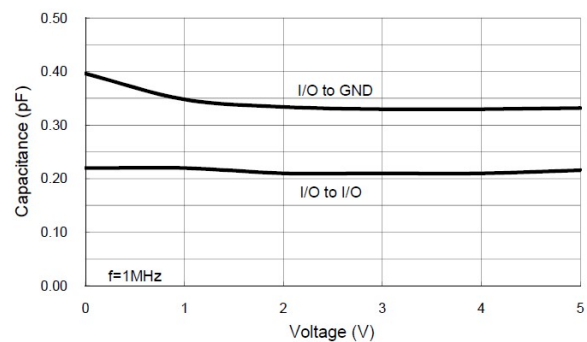


Fig 5 ESD Clamping of I/O to GND  
(+8kV Contact per IEC 61000-4-2)

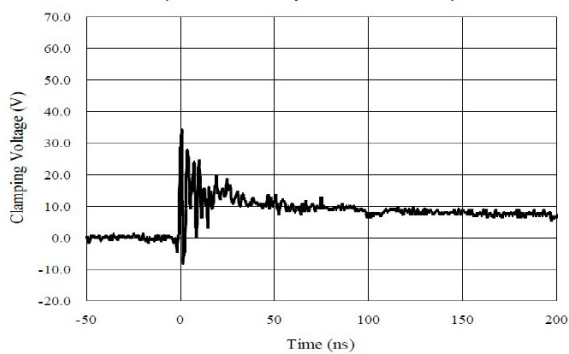
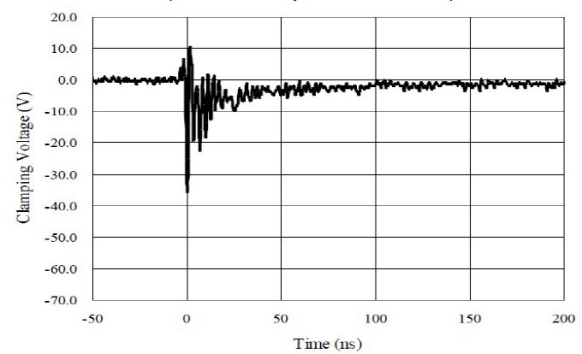
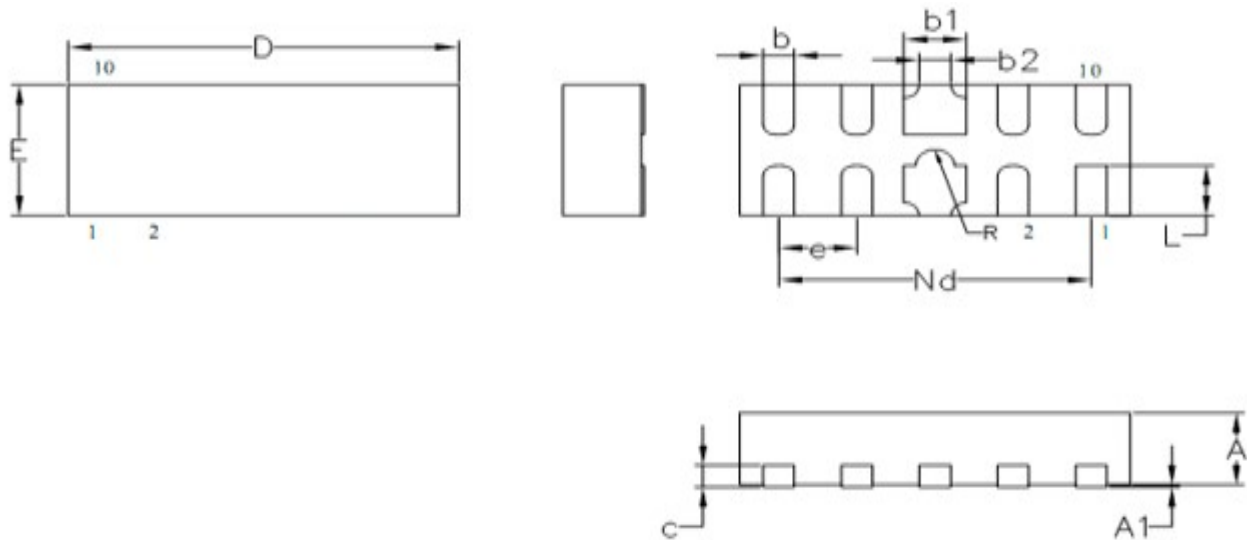


Fig 6 ESD Clamping of I/O to GND  
(-8kV Contact per IEC 61000-4-2)



**DFN2510 PACKAGE OUTLINE DIMENSIONS**


| Symbol | Dimensions (mm) |       |      |
|--------|-----------------|-------|------|
|        | Min.            | Nom.  | Max. |
| D      | 2.45            | 2.50  | 2.55 |
| E      | 0.95            | 1.00  | 1.05 |
| b1     | 0.35            | 0.40  | 0.45 |
| b2     | 0.20REF         |       |      |
| b      | 0.15            | 0.20  | 0.25 |
| L      | 0.33            | 0.38  | 0.43 |
| Nd     | 2.00BSC         |       |      |
| e      | 0.50BSC         |       |      |
| R      | 0.10            | 0.125 | 0.15 |
| A      | 0.45            | 0.50  | 0.55 |
| c      | 0.15REF         |       |      |
| A1     | 0.00            | -     | 0.05 |